

**Abstract of the Disclosure**

In a high-frequency switching module for use mainly in a communications apparatus and a high-frequency apparatus equipped with the same, the high-frequency switching module has a group of high-frequency terminals provided on the mounting side surface of a multi-layer assembly of which the lateral sides are formed as no-electrode provided sides excluding the high-frequency terminals. Thus, the high-frequency switching module and the high-frequency apparatus equipped with the same are less susceptible to the external effect.

PCT/JP2008/052022